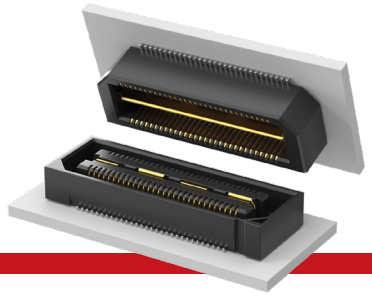
QSTRIP®

NRZ 25 Gbps



(0.50 mm) .0197" PITCH • QTH/QSH SERIES

QTH
Board Mates:
QSH

QSH
Board Mates:
QTH

QTH/QSH
Cable Mates:
HQCD, HQDP

Standoffs:
SO

SPECIFICATIONS

Insulator Material:
Liquid Crystal Polymer
Contact Material:
Phosphor Bronze
Plating:
Au or Sn over
50 µ" (1.27 µm) Ni
Operating Temp Range:
-55 °C to +125 °C
Current Rating:
Contact:
2 A per pin (2 pins powered)
Ground Plane:
25 A per ground plane
(1 ground plane powered)
Voltage Rating:
175 VAC/247 VDC
Max Cycles:
100

PROCESSING

Lead–Free Solderable:
Yes
SMT Lead Coplanarity:
(0.10 mm) .004" max
(030-060)
(0.15 mm) .006" max (090)*
*(.004" stencil solution may be available; contact ipg@samtec.com)
Board Stacking:
For applications requiring more than two connectors contact ipg@samtec.com

STANDARDS

PISMO™ 1:
Visit samtec.com/standards for more information.

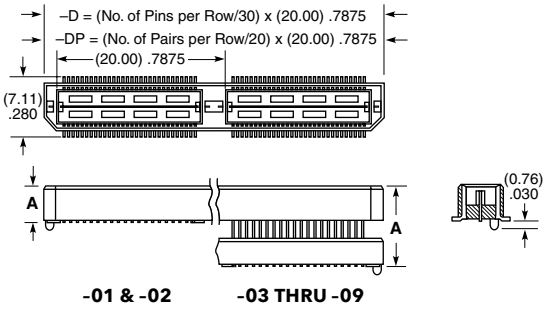
10 YEAR MFG
EXTENDED LIFE PRODUCT
HIGH MATING CYCLES

Note:
Some lengths, styles and options are non-standard, non-returnable.

QTH	PINS PER ROW NO. OF PAIRS	LEAD STYLE	PLATING OPTION	TYPE	A	OTHER OPTIONS	"X"R
	–030, –060, –090 (60 total pins per bank = –D) **–020, –040, –060** (20 pairs per bank = –D–DP)	Specify LEAD STYLE from chart	**–F** = Gold flash on contact, Matte Tin on tail **–L** = 10 µ" (0.25 µm) Gold on contact, Matte Tin on tail **–C** = 50 µ" (1.27 µm) Electro-Polished Selective Gold on contact, Matte Tin on tail (passes 10 year MFG testing)	**–D** = Single-Ended **–D-DP** = Differential Pair (–01 only)		**–K** = (7.00 mm) .275" DIA Polyimide film Pick & Place Pad (Not available with -05 & -07 lead style) **–L** = Latching Option (–01 lead style only) (Not available on –060 (–D–DP) & –090)	Leave blank for Tray Packaging **–TR** =Tape & Reel (Not available with –05 & –07 lead style) **–FR** = Full Reel Tape & Reel (must order max. quantity per reel; contact Samtec for quantity breaks) (Not available with –05 & –07 lead style)

QTH LEAD STYLE	A	HEIGHT WITH QSH*
–01	(4.27) .168	(5.00) .197
–02	(7.26) .286	(8.00) .315
–03	(10.27) .404	(11.00) .433
–04	(15.25) .600	(16.00) .630
–05	(18.26) .718	(19.00) .748
–07	(24.24) .954	(25.00) .984
–09	(13.26) .522	(14.00) .551

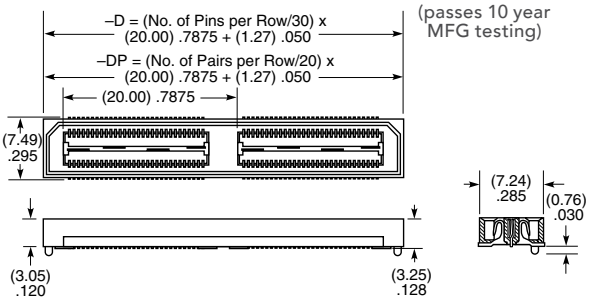
*Processing conditions will affect mated height. See SO Series for board space tolerances.



-01 & -02 -03 THRU -09

View complete specifications at: **samtec.com?QTH**

QSH	PINS PER ROW NO. OF PAIRS	01	PLATING OPTION	TYPE	A	OTHER OPTIONS	"X"R
	–030, –060, –090 (60 total pins per bank = –D) **–020, –040, –060** (20 pairs per bank = –D–DP)		**–F** = Gold flash on contact, Matte Tin on tail **–L** = 10 µ" (0.25 µm) Gold on contact, Matte Tin on tail **–C** = 50 µ" (1.27 µm) Electro-Polished Selective Gold on contact, Matte Tin on tail (passes 10 year MFG testing)	**–D** = Single-Ended **–D–DP** = Differential Pair		**–K** = (8.25 mm) .325" DIA Polyimide film Pick & Place Pad **–L** = Latching Option (Not available on –060 (–D–DP) & –090)	Leave blank for Tray Packaging **–TR** =Tape & Reel (N/A –05 to –07 lead style) **–FR** = Full Reel Tape & Reel (must order max. quantity per reel; contact Samtec for quantity breaks))



View complete specifications at: **samtec.com?QSH**

Unless otherwise approved in writing by Samtec, all parts and components are designed and built according to Samtec's specifications which are subject to change without notice.